

ABSTRACT**RESIN COMPOSITION**

Provided is a resin composition comprising (A) an epoxy compound, (B) an epoxy resin, and (C) a photocationic polymerization initiator. Preferably, this resin composition has a moisture content of 1000 ppm or less and a chlorine content of 1000 ppm or less. This resin composition is an energy beam-curable resin composition having accurate coating properties, excellent adhesiveness, low moisture permeability, excellent adhesive durability, and excellent storage stability.